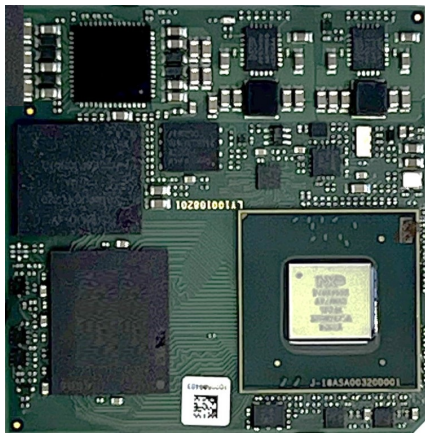


## TRIA OSM-LF-IMX95

NXP® i.MX 95 Arm®  
Cortex® -A55 / M7 / M33

45 x 45 mm



4-6 W

-40 +85



## Highlights

- Hexa core Arm Cortex-A55 up to 2.0GHz
- Arm Cortex-M7 Real Time Processor at 800MHz
- Arm Cortex-M33 Real Time Processor at 333MHz
- NXP eIQ Neutron Neural Processing Unit.
- NXP Image Signal Processor
- Arm Mali Graphics Processing Unit
- Video Processing Unit up to 4k decode/encode
- Up to 16GB LPDDR5 SDRAM with inline ECC
- Up to 256GB eMMC Flash
- Dual-channel LVDS, MIPI-DSI x4
- Dual MIPI CSI-2 Camera interface
- 2x PCI Express x1 Gen. 3
- 1x USB 3.0/2.0 Host/Device interface
- 1x USB 2.0 Host/Device interface
- 2x Gigabit Ethernet (RGMII)
- 1x up to 10 Gigabit Ethernet (SerDes)
- 3x CAN-FD Interface, 2x SDIO interface
- 2x I2S Audio Interface
- 24x GPIO, 6x ADC, 4x PWM
- UART, SPI, QSPI, I2C

## Technical Data

<b>Technology</b>	ARM
<b>Formfactor</b>	OSM-LF, 662 Contacts, RM 1,25 mm
<b>CPU</b>	<p>NXP i.MX 95 Arm Cortex-A55 Applications Processor</p> <ul style="list-style-type: none"> <li>• 6/4 cores, 1.8 - 2.0 GHz, with ISP, NPU, GPU, VPU, DC, dual-core option*</li> <li>• 6/4 cores, 1.8 - 2.0 GHz, with ISP, NPU, VPU</li> <li>• 6/4 cores, 1.8 - 2.0 GHz, with NPU, GPU, VPU, DC</li> <li>• 6/4 cores, 1.8 - 2.0 GHz, with NPU, dual-core option</li> </ul> <p>*dual-core part available in commercial temperature and 1.0 GHz          Arm Cortex-M7 Real Time Processor at 800MHz          Arm Cortex-M33 Real Time Processor at 333MHz</p> <p>NXP eIQ Neutron Neural Processing Unit (processor SKU dependent)          NXP Image Signal Processor (processor SKU dependent)</p>
<b>Chipset</b>	SOC
<b>RAM</b>	Up to 16GB 6400MT/s LPDDR5 SDRAM, soldered, inline ECC support
<b>Flash</b>	Up to 256GB eMMC 5.1 Flash QSPI NOR/NAND Flash (optional)
<b>Storage Interfaces</b>	2x MMC/SD/SDIO
<b>USB</b>	1x USB 2.0 Host/Client, 1x USB 2.0 Host/Client or 1x USB 3.0 Host/Client
<b>Serial Interfaces</b>	3x UART Console with Rx, Tx only 2x UART with 2-wire hand shake (RTS/CTS)
<b>Bus Interfaces</b>	2x PCI Express x1 Gen.3 lane 5x I2C up to 400 Kbit/s (2x for GP) 2x CAN-FD / CAN 2.0B 1x CAN-FD / CAN 2.0B on vendor defined pins 1x SPI (with two chip selects) 1x QSPI/SPI (with two chip selects)
<b>Display Controller</b>	Arm Mali G310 GPU (OpenGL® ES 3.2, Vulkan®1.2, OpenCL 3.0), (processor SKU dependent) Video Processing Unit with up to 4k decode/encode (processor SKU dependent)
<b>Display Interfaces</b>	MIPI-DSI Display Interface, 4 lanes, up to 3840x1440p60 Dual-channel 18/24 bit LVDS interface, up to 1080p60
<b>Network Interface</b>	2x Gigabit Ethernet (RGMII interface) 1x up to 10 Gigabit Ethernet (SerDes interface) with TSN support
<b>Audio Interface</b>	2x I2S Audio
<b>Security Device</b>	Advanced Security, Safety, and Reliability integrated in the SOC Integrated EdgeLock secure enclave to simplify implementation of security critical functions like secure boot, cryptography, trust provisioning, run-time attestation, key management services, provision for secure remote management, secure over-the-air updates (OTA) and dedicated cryptographic engine.
<b>Miscellaneous</b>	Watchdog Timer for system reset (programmable, 1s ... 600s) Temperature compensated RTC 24x GPIO, configurable as input or output 4x PWM 2x ADC inputs (12-bit) 4x ADC inputs (12-bit) on vendor defined pins 64kbit ID EEPROM on I2C bus MIPI CSI-2 camera interface (CSIA, 4-lane) MIPI CSI-2 camera interface (CSIB, 4-lane), shared (onboard switch) with MIPI-DSI interface

<b>Feature Highlights</b>	OSM V1.2, Size-L compatible
<b>OS Support</b>	Linux Board Support Package Android support on request
<b>Power Requirement</b>	Power Supply +5V +/-5% Power Consumption 4-6 W typ. (depending on CPU)
<b>Environment</b>	Temperature Range: Commercial: 0° ... 70°C (operating) -20° ... 85°C (storage) Extended: -25° ... 85°C (operating) -40° ... 85°C (storage) Industrial: -40° ... 85°C (operating) -40° ... 85°C (storage) Humidity: 5 ... 95% (operating, non condensing) 5 ... 95% (storage, non-condensing)
<b>Dimensions</b>	45 x 45 mm
<b>Certificates</b>	UL /CE
<b>Carrier</b>	TRIA OSM-SB-EP5-95 (coming soon)

Technical Data for TRIA OSM-LF-IMX95

## Order Reference

Order No.	Description	Reference	Status*
121781	OSM module Size L (45x45 mm) with i.MX 9556 (6x A55 @ 1.8 GHz, NPU, GPU, VPU, Display), w/ 2.5 GB (SERDES/SGMII), 4GB LPDDR5 (w/ inline ECC support), 8GB eMMC, no NOR/NAND flash, LVDS, DSI, CSI-2 (Port A), 2x GbE (RGMII), 2x PCIe, 2x CAN-FD, 1x USB 3.0 OTG (Port C) + 1x USB 2.0 OTG (Port A), PCIe Clock available, Industrial Temperature (-40..+85°C)	MSC OSM-LF-IMX95-HC5-23N0A10I PCBFTX	PV
121782	OSM module Size L (45x45 mm) with i.MX 9596 (6x A55 @ 1.8/2.0 GHz, ISP, NPU, GPU, VPU, Display), w/ 2.5 GB (SERDES/SGMII), 8GB LPDDR5 (w/ inline ECC support), 64GB eMMC, no NOR/NAND flash, LVDS, DSI, CSI-2 (Port A), 2x GbE (RGMII), 2x PCIe, 2x CAN-FD, 1x USB 3.0 OTG (Port C) + 1x USB 2.0 OTG (Port A), PCIe Clock available, Industrial Temperature (-40..+85°C)	MSC OSM-LF-IMX95-HC9-36N0A10I PCBFTX	PV

Ordering Information for TRIA OSM-LF-IMX95

\*PV = Preferred variant; OR = on Request (in OEM quantities only)



Please ask for further variants!

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